

Form PTOL 449 (Patent Office Use Only) Information Disclosure Statement BY APPLICANT (Use several sheets if necessary)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	Attorney Docket Number TEGL-01071US3	Serial/Patent Number 09/880,584
	Applicant/Patent Owner Stephen P. DeOrnellas		
	Filing/Issue Date June 13, 2001	Group Art Unit 1763	

U.S. PATENTS

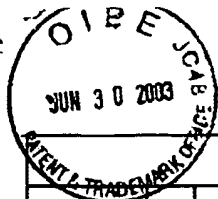
Examiner Initial		Patent Number	Issue Date	First Named Inventor	CLASS	SUBCLASS	FIGS
gag	1	4,208,241 ✓	6/17/1980	Harshbarger, et al.			
	2	4,457,359 ✓	7/3/1984	Holden			
	3	4,508,161 ✓	4/2/1985	Holden			
	4	4,512,391 ✓	4/23/1985	Harra			
	5	4,535,834 ✓	8/20/1985	Turner			
	6	4,542,298 ✓	9/18/1985	Holden			
	7	4,680,061 ✓	7/14/1987	Lamont, Jr.			
	8	4,743,570 ✓	5/10/1988	Lamont, Jr.			
	9	5,266,157 ✓	11/1993	Kodomura			
	10	5,270,266 ✓	12/1993	Hirano, et al.			
	11	5,421,401 ✓	6/1995	Sherstinsky, et al.			
	12	5,447,570 ✓	9/1995	Schmitz, et al.			
	13	5,775,416 ✓	7/1998	Heimanson, et al.			
	14	6,147,506 ✓	11/2000	Ahmad et al.			

U.S. PATENT PUBLICATIONS

Examiner Initial	Patent Application Publication Number	Publication Date	Applicant

PENDING U.S. PATENT APPLICATIONS

Examiner Initial	Application Number	Filing Date	First Named Inventor	Petition to Expunge? Yes No



FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Publication Date	Country	Class	Subclass	Repub- lication Yes/No
GRG	JP-7-130712 /	5/19/1995	Japan			

OTHER DOCUMENTS (Include author (if any), title, publisher and place of publication, date and pertinent pages)

GRG	Ohno, et al. <i>Reactive Ion Etching of Cooper Films in SiCl₄ and N₂</i> , Japanese Journal of Applied Physics, Vol. 28, No. 6, June 1978, pp. 11070-1072 /
GRG	Krogh, et al. <i>Spectroscopic Diagnostic of Temperature-Controlled Trench Etching of Silicon</i> , Plasma Chemistry Plasma Processes, 10(2), 1990, pp. 231-233, 239 /

Examiner

George Goudreau

Date Considered

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*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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